

In the Claims

Claims 1-15 (withdrawn).

16. (Currently Amended) An integrated circuit chip comprising:
a bumped side having a passivation surface on which a plurality of conductive bumps are disposed; and
a layer adhesive that covers the bumped side of the [circuit substrate] integrated circuit chip, the adhesive having a primary surface that is substantially parallel to the passivation surface, and the conductive bumps having exposed contact regions that are not covered by the adhesive, wherein the exposed contact regions of the conductive bumps have a rounded profile.
17. (Original) The integrated circuit chip of claim 16, wherein the primary surface of the adhesive is polished.
18. (Original) The integrated circuit chip of claim 16, wherein the conductive bumps have heights greater than a thickness of the adhesive.
19. (Original) The integrated circuit chip of claim 16, wherein portions of the conductive bumps project outward from the primary surface of the adhesive such that a stand-off exists between the rounded profile of the conductive bumps and the primary surface of the adhesive.

Claims 20-23 (withdrawn).